BT151-650LTN

SCR

Rev.03 - 02 September 2021

Product data sheet

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a TO220 plastic package intended for use in applications requiring good bidirectional blocking voltage and high current surge capability with high thermal cycling performance and high junction temperature capability ($T_{j(max)}$ = 150 °C).

2. Features and benefits

- High junction operating temperature capability ($T_{j(max)}$ = 150 °C)
- Good bidirectional blocking voltage capability
- High current surge capability
- High thermal cycling performance
- Planar passivated for voltage ruggedness and reliability

3. Applications

- Capacitive Discharge Ignition (CDI)
- Crowbar protection
- Inrush protection
- Motor control
- Voltage regulation
- High junction operating temperature capability ($T_{j(max)}$ = 150 °C)

4. Quick reference data

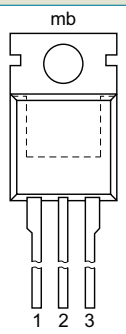
Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
Absolute maximum rating				
V_{RRM}	repetitive peak reverse voltage		650	V
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 134$ °C; Fig. 1; Fig. 2; Fig. 3	12	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig. 4; Fig. 5	120	A
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms	132	A
T_j	junction temperature		150	°C

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 7		1.5	-	5	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C; Fig. 9		-	-	20	mA
V_T	on-state voltage	I_T = 12 A; T_j = 25 °C; Fig. 10		-	1.15	1.5	V
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 436 V; T_j = 150 °C; R_{GK}= 100 Ω; (V_{DM} = 67% of V_{DRM}); exponential waveform;		500	1000	-	V/µs

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BT151-650LTN	TO220	BT151-650LTNQ	Tube	50	SOT78	13-Jun-2008

7. Marking

Table 4. Marking codes

Type number	Marking codes	
	Assembly factory: d	Assembly factory: A
BT151-650LTN	BT151 650LTN PJdxxxx xx	BT151 650LTN PJAxxxx xx

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		650	V
V_{RRM}	repetitive peak reverse voltage		650	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 134$ °C;	7.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 134$ °C; Fig. 1; Fig. 2; Fig. 3	12	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25$ °C; $t_p = 10$ ms; Fig. 4; Fig. 5	120	A
		half sine wave; $T_{j(init)} = 25$ °C; $t_p = 8.3$ ms	132	A
I^2t	I^2t for fusing	$t_p = 10$ms; sine wave	72	A^2s
dI_T/dt	rate of rise of on-state current	$I_G = 10$mA	50	A/µs
I_{GM}	peak gate current		2	A
V_{RGM}	peak reverse gate voltage		18	V
P_{GM}	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T_{stg}	storage temperature		-40 to 150	°C
T_j	junction temperature		150	°C

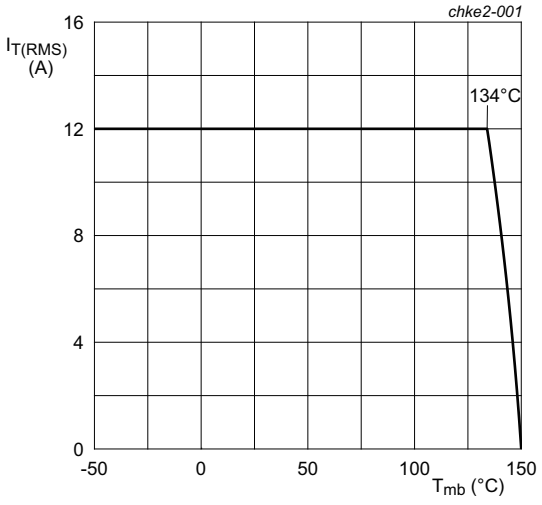
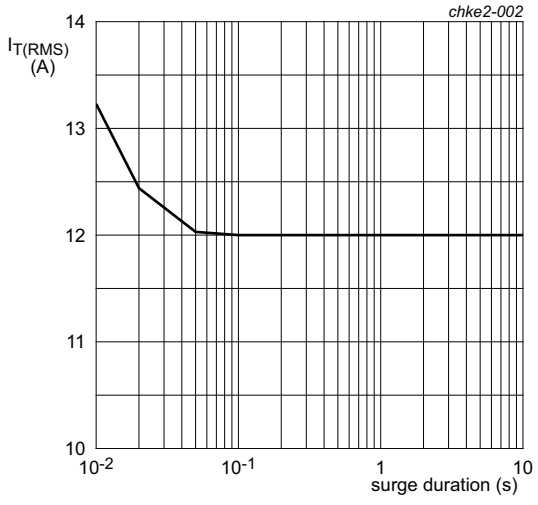
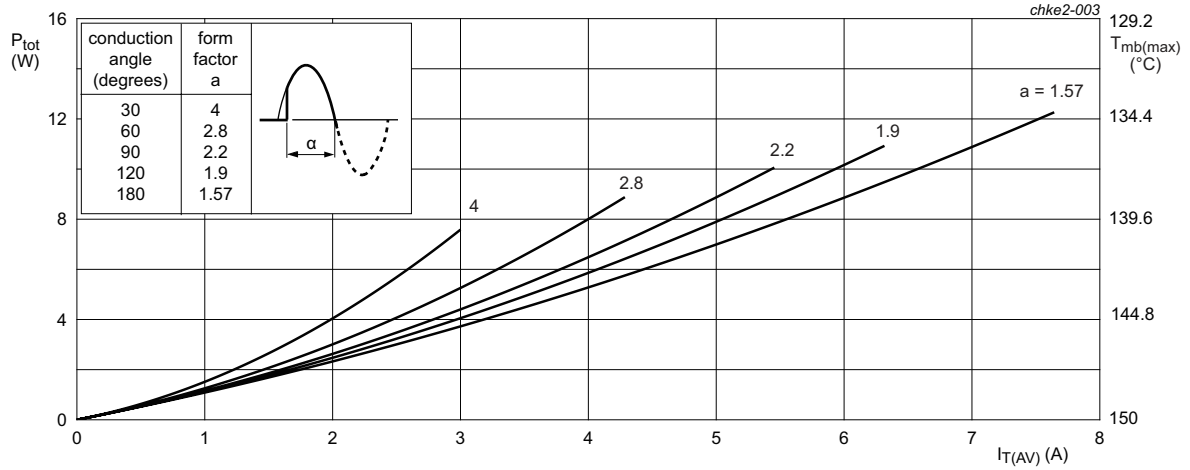


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz; T_{mb} = 134 °C

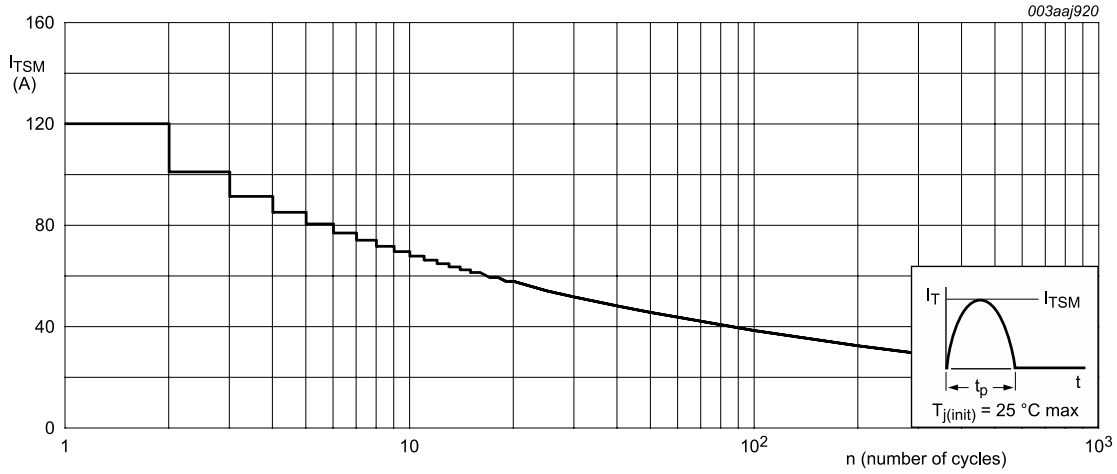
Fig. 2. RMS on-state current as a function of surge duration; maximum values



α = conduction angle

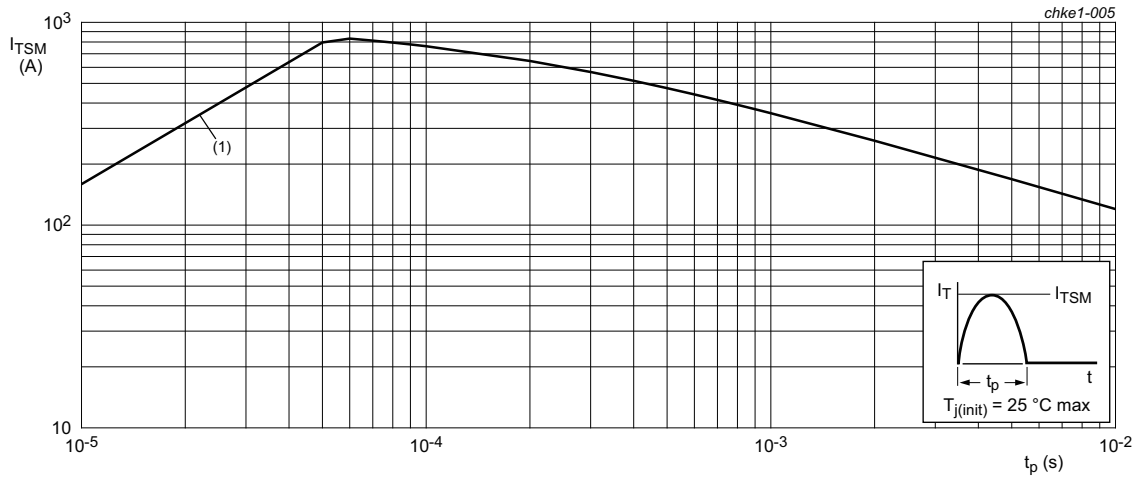
a = form factor = $I_{T(RMS)}$ / $I_{T(AV)}$

Fig. 3. Total power dissipation as a function of average on-state current; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 10$ ms ;

(1) dI_T/dt limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6		-	-	1.3	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

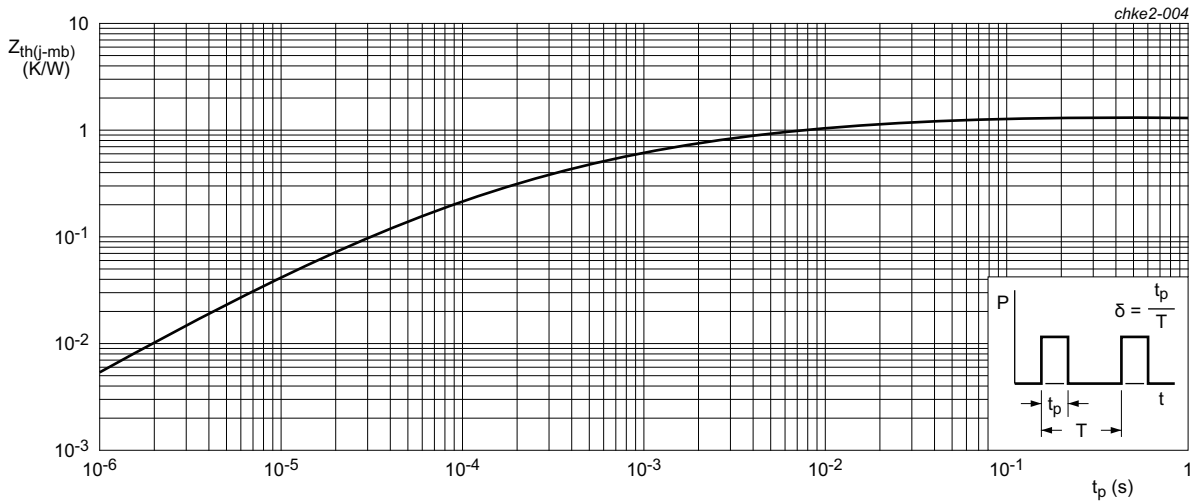


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 7		1.5	-	5	mA
I_L	latching current	V_D = 12 V; I_G = 0.1 A; T_j = 25 °C; Fig. 8		-	-	40	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C; Fig. 9		-	-	20	mA
V_T	on-state voltage	I_T = 12 A; T_j = 25 °C; Fig. 10		-	1.15	1.5	V
V_{GT}	gate trigger voltage	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 11		-	0.65	1	V
		V_D = 400 V; I_T = 0.1 A; T_j = 150 °C		0.2	0.4	-	V
I_D	off-state current	V_D = 650 V; T_j = 150 °C		-	-	1	mA
I_R	reverse current	V_D = 650 V; T_j = 150 °C		-	-	1	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 436 V; T_j = 150 °C; R_{GK} = 100 Ω; (V_{DM} = 67% of V_{DRM}); exponential waveform;		500	1000	-	V/µs
		V_{DM} = 436 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit		50	-	-	V/µs
t_{gt}	gate-controlled turn-on time	I_{TM} = 12 A; V_D = 650 V; I_G = 100 mA; $(dI_G/dt)_M$ = 5 A/µs; T_j = 25 °C			2	-	µs
t_q	commutated turn-off time	V_{DM} = 436 V; T_j = 125 °C; I_{TM} = 12 A; V_R = 25 V; dV_D/dt = 30 V/µs; $(dI_T/dt)_M$ = 30 A/µs; $R_{GK(ext)}$ = 100 Ω ; (V_{DM} = 67% of V_{DRM})			70	-	µs

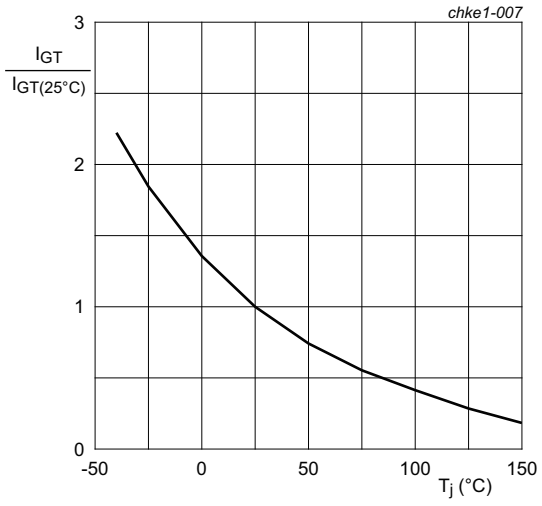


Fig. 7. Normalized gate trigger current as a function of junction temperature

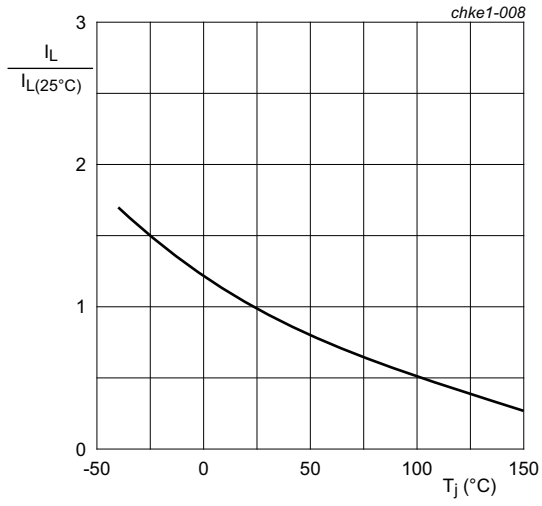


Fig. 8. Normalized latching current as a function of junction temperature

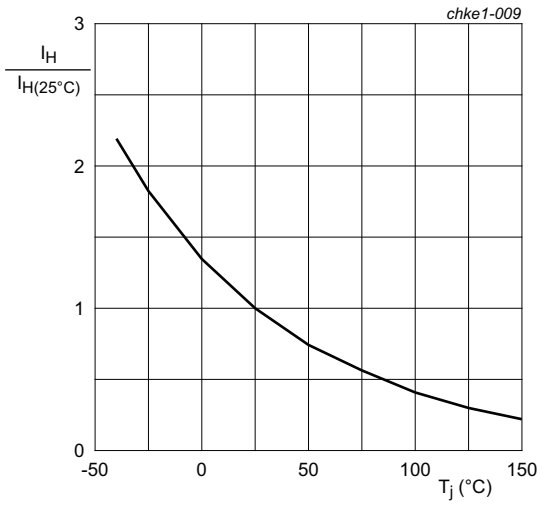
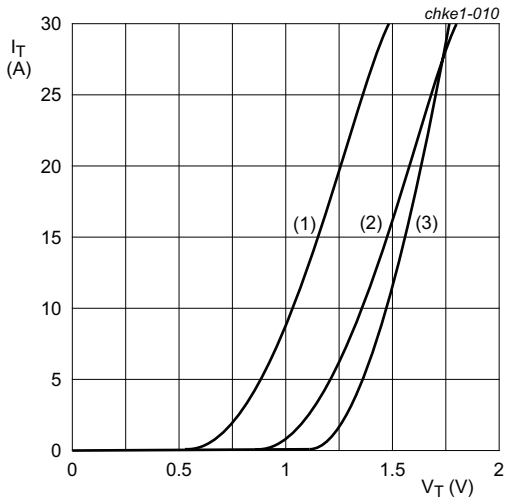


Fig. 9. Normalized holding current as a function of junction temperature



V_o = 1.008 V; R_s = 0.0317 Ω
(1) T_j = 150 °C; typical values
(2) T_j = 150 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

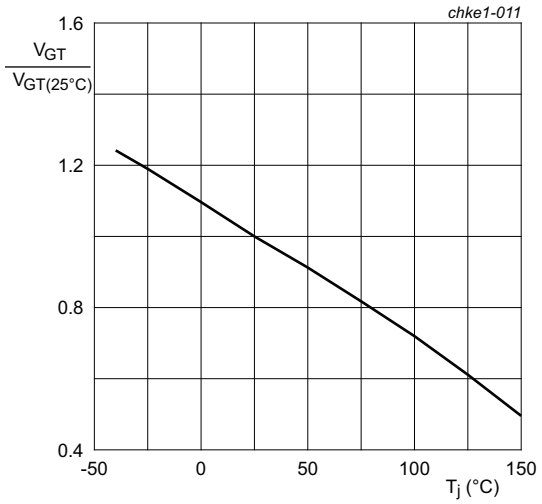
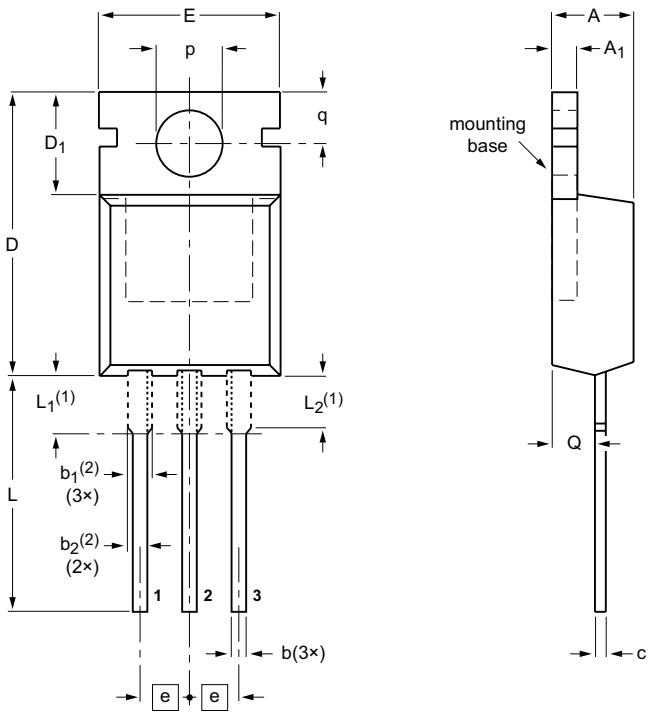


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

11. Package outline

Assembly factory: d & A

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB **SOT78**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b	b_1(2)	b_2(2)	c	D	D_1	E	e	L	L_1(1)	L_2(1) max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

Notes

1. Lead shoulder designs may vary.
2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT78		3-lead TO-220AB	SC-46			~~08-04-23~~ 08-06-13

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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13. Contents

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